

# VCSEL Device and System Design for Manufacturing

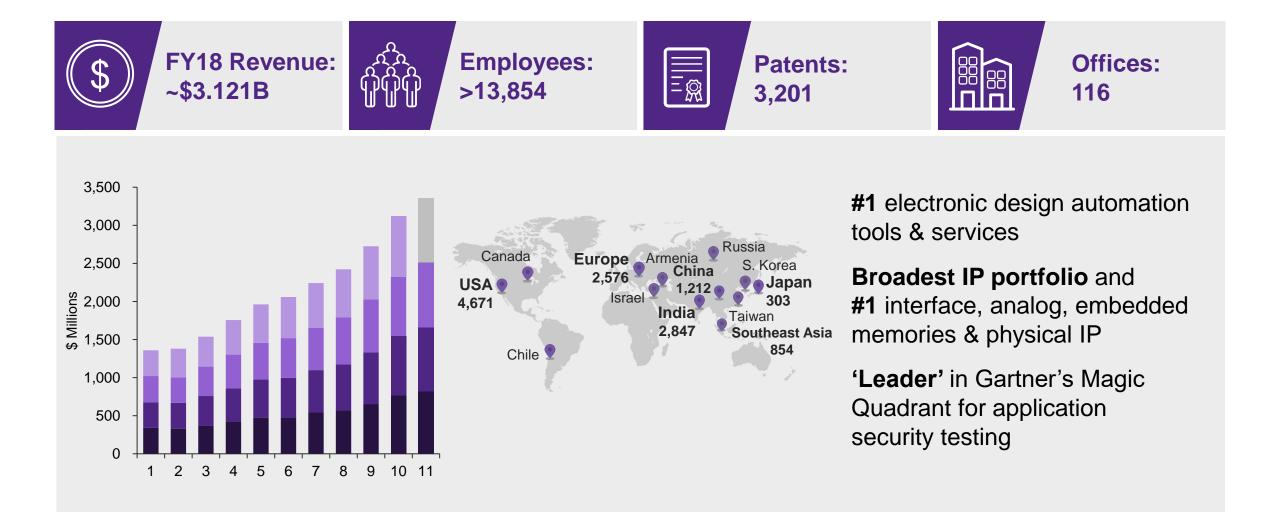
Multi-level modeling solution

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# Synopsys Today: From Silicon to Software

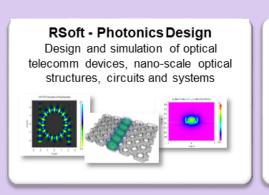


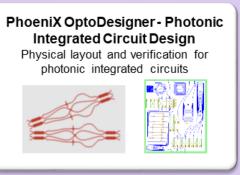


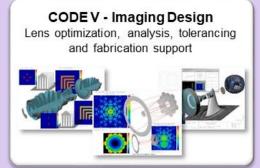
#### Synopsys Sees Optics and Photonics as a Key Enabling Technologies

Entered the Field in 2010

- Acquired Optical Research Associates, Brandenburg, and RSoft Design Group
  - -Full spectrum of optical and photonic design solutions and services
- Expanded portfolio for photonic IC design by acquiring PhoeniX Software in 2018
  - -Complete PIC design flow from a single vendor with one support channel
- Largest dedicated optics and photonics software development and support team













- Introduction: History and Applications
- Design Objectives and Choice of Design Flow
- VCSEL: Circuit- and System-level Modeling
- **VCSEL**: Device-level Modeling
- Conclusion

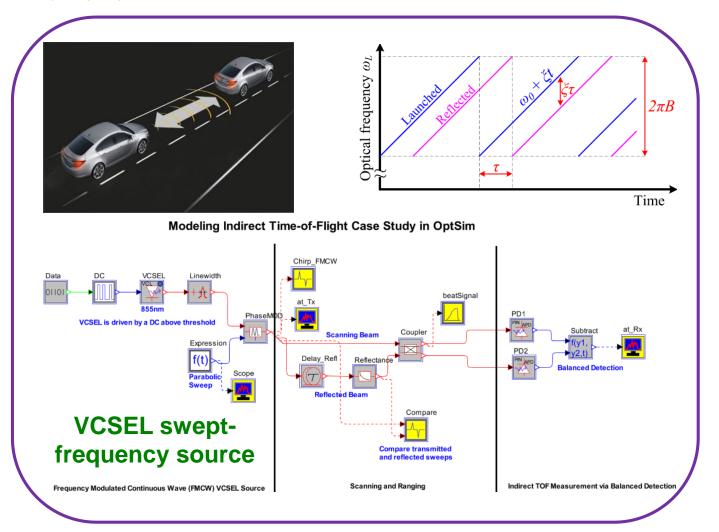


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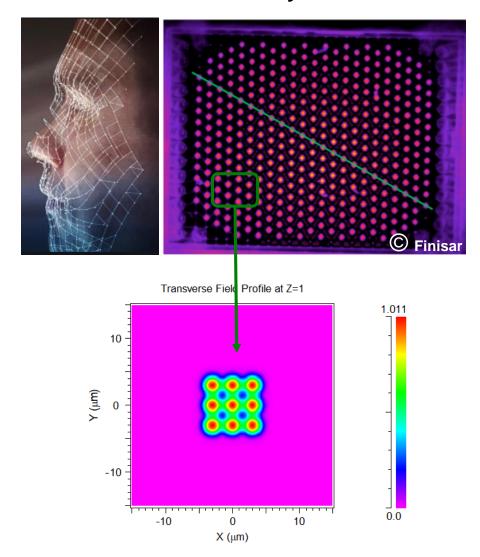


# **History and Application(s)**

ToF and LiDAR



#### FaceID: VCSEL arrays

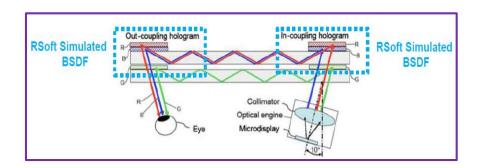




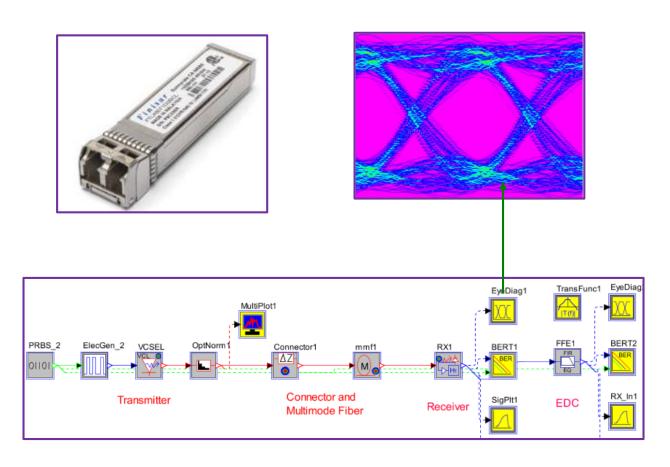
# **History and Application(s)**

AR/VR





#### High-speed Transceiver





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#### **Problems to Solve**

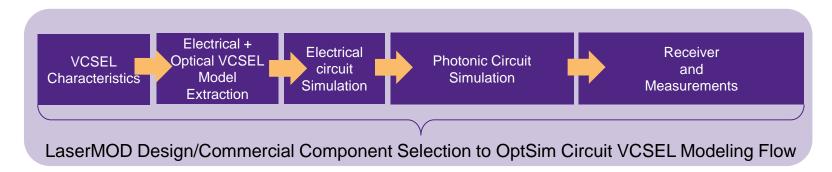
- Predictive models capturing thermal, electrical and optical behavior needed to enable design for manufacturing (DfM)
- Modeling presents several challenges:
  - Interdependence of physical parameters makes parameter extraction difficult
  - Thermal effects, packaging parasitics must be accounted for
  - Manufacturing variability results in performance variations. Must be able to predict performance bounds for given tolerances
  - Driver circuit dynamics play crucial role in modulation bandwidth and power output
  - Often optical and electrical design teams are different but inter-dependent
  - Interference from reflections affect power distribution and phase noise



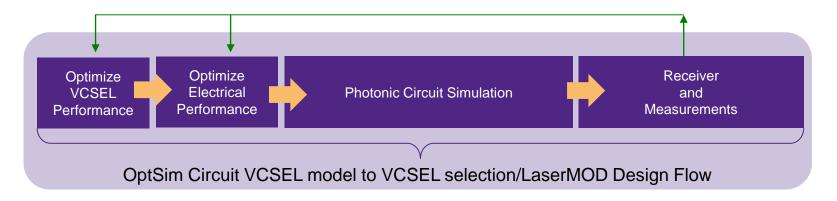
# Design Objectives and the Choice of Flow

Two possible approaches

1. Bottom-up: Starting with known VCSEL specs, evaluate system performance:

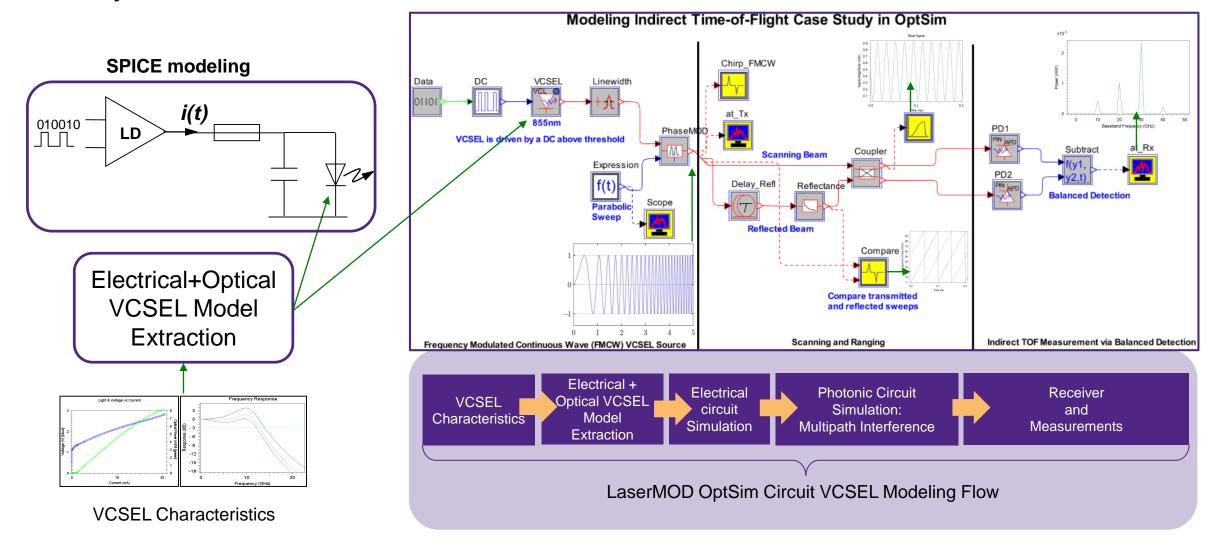


2. Top-down: Starting with targeted system performance, evaluate VCSEL selection/design:



# **Example: Optical System Design Flow**

ToF System for LiDAR



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# VCSEL: Circuit- and System-level Modeling

 Interdependence of parameters makes modeling and parameter extraction a complex challenge

| VCSEL Parameter                           | Parameter Dependency  |
|---|---|
| Threshold current                         | Photon lifetime, carrier lifetime, gain coefficient, carrier transparency number  |
| Output power                              | Output power coupling coefficient, Photon lifetime, carrier lifetime, gain coefficient, carrier transparency number, test current |
| P-I Slope                                 | Photon lifetime, Output power coupling coefficient  |
| Turn-on Delay                             | Photon lifetime, carrier lifetime, gain coefficient, carrier transparency number, test current                                    |
| Thermal gain constant                     | Gain constant and Empirical fitting parameters  |
| Temperature dependent transparency number | Carrier transparency number and Empirical fitting parameters  |
| Thermal leakage current                   | Leakage current factor, temperature, and Empirical fitting parameters   |

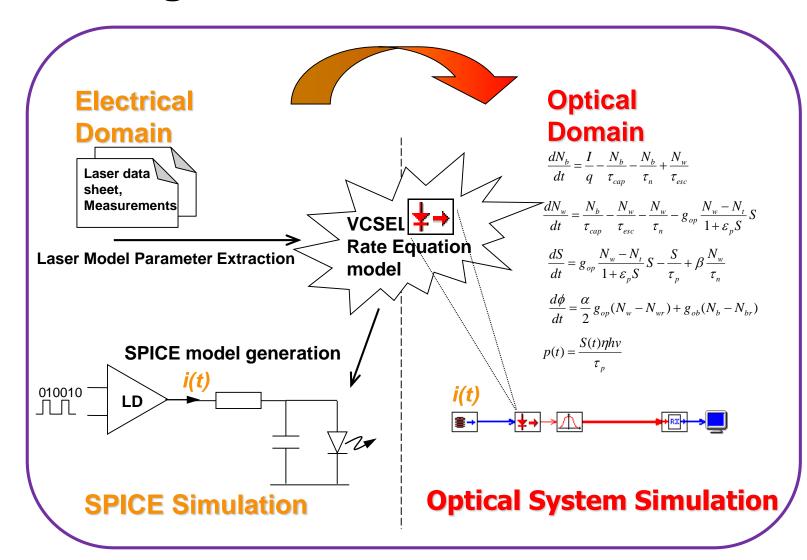


# VCSEL: Circuit- and System-level Modeling

- VCSEL behavior is highly sensitive to drive conditions and operating temperature. Modeling must capture
  - Driving scheme, parasitics, thermal dependence of gain and carrier leakage, device self-heating, phase-noise like impairments from multipath interference (reflections)
- Datasheets mostly give measured behavior, not all physical parameters available. Device geometries are often unknown to system designers (i.e., can't use a device modeling tool)
- VCSEL arrays are often driven by common electronics, loading and power-delivery analyses vital
- Co-packaged optics require driver electronics be on the same chip
- Electronics designers often not comfortable with photonic models, and their EDA tools don't have photonic components
- How to facilitate inter-domain modeling? How to extract physical parameters from datasheet parameters?

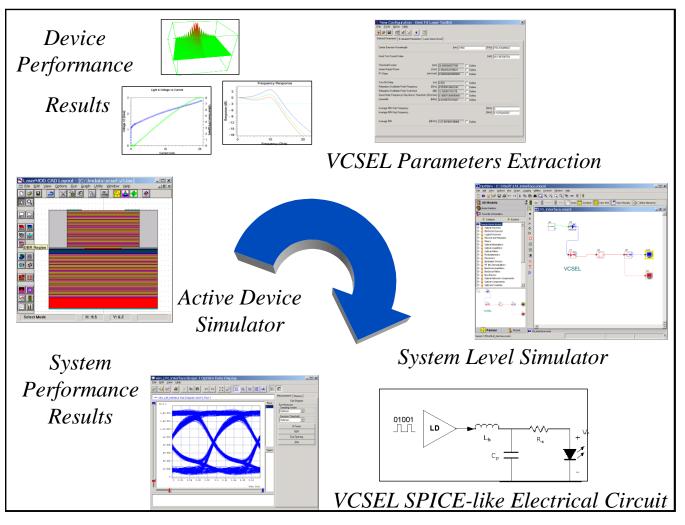


# **Starting from a Datasheet**

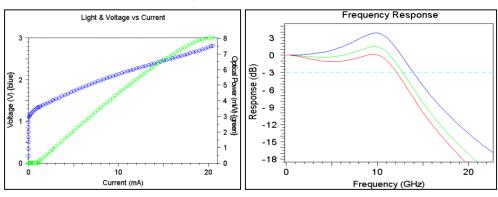


- Rate-equation laser model parameters extracted from data sheet information
- Rate-equation laser model converted into an equivalent circuit (SPICE or equivalent circuit simulation tool format) that can be simulated in the electrical domain
- Identical rate-equation laser model shared between electrical and optical simulation includes both electrical and optical characteristics
- Effective aid to laser driver design
- Simulation of the TRUE driving conditions of the laser

# Starting from a Device Model



- OptSim uses LaserMOD results:
  - L-I curve
  - S21 curve frequency response
  - Material Gain versus Temperature and Carrier density



- Through optimization OptSim can extract the VCSEL rate equation parameters necessary to simulate at the system-level
- Rate-equation VCSEL model converted to electrical equivalent circuit model for EDA

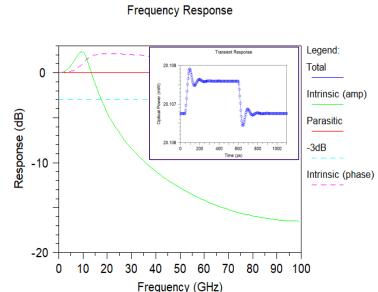


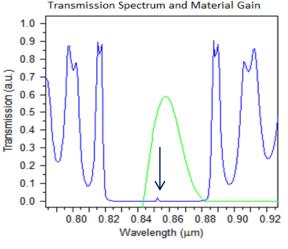
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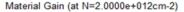


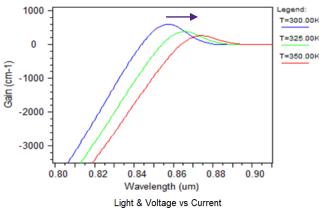
#### **Device Level Simulation of VCSELs**

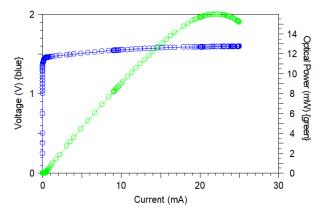
- Design flow begins with alignment of material gain and cavity resonances
  - Transmission spectrum of VCSEL cavity indicates location of modes
  - Alignment with material gain determines Quantum Well and Cavity properties
- Steady-state simulation of the physics produces the LIV curves
  - Material gain will red-shift with temperature increase (due to self-heating)
  - This leads to roll-off of the L-I curve, since cavity resonances shift only slightly
- Transient simulation produces the time and frequency responses
  - Determines the 3dB bandwidth
  - Relaxation oscillation frequency
  - Turn-on delay
  - Capacitance and Resistance vs Voltage
- Creation of Circuit Model For System and Circuit Level Simulation





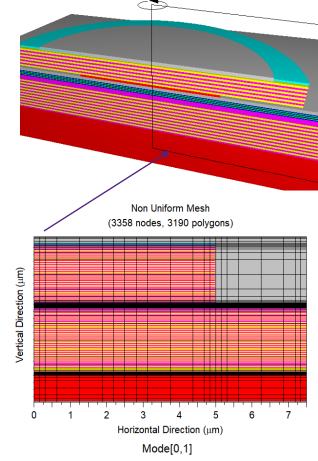


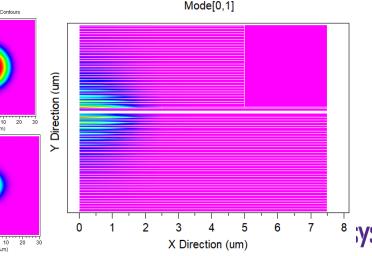




#### **Device Level Simulation of VCSELs**

- Rigorous simulation of the discretized structure on a mesh
  - Geometric definition of the device structure
  - Specification of material system, alloy composition, and doping
- Cylindrical symmetry may be exploited to reduce computational time
  - The vertical & radial directions are meshed
  - Physics solved in cylindrical coordinates, so the solution is a "body of revolution"
- Gain / optics / thermo-electric transport must be solved self-consistently
  - Quantum Well Gain solved via the K●P method (8x8 band)
  - Photon Rate Equations and Cavity modes via Finite Element Method (FEM)
  - Poisson, Continuity Equations, and Lattice Heat equation
- Gives spatial solution of physics throughout the device
  - carrier densities (spatial hole burning), temperature profiles,
  - current contours, recombination, ...
- Provides steady state and dynamic performance analysis
  - LIV curves (roll-off), near fields, far fields,
  - transient and frequency responses, ..., and circuit models





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#### Conclusion

- Diverse range of VCSEL applications demands mixed-level, multi-domain modeling
- Co-simulation between optical system simulation tool (e.g. OptSim) and EDA tools (e.g. HSPICE, Spice, ADS, and Spectre) with option of using device-level laser modeling tool (e.g. LaserMOD) lead to manufacturing-oriented design cycle
- Device and circuit designers can optimize designs for maximum overall system performance
- System designers can determine system performance based on highly accurate device and circuit models and optimize system designs according to actual components to be used in system
- Greatest accuracy in end-to-end device/circuit/system simulation and design for best performance, and reduction in cost and time-to-market





# Thank You



# This presentation was presented at EPIC Meeting on VCSELs Technology and Applications 2019

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